T-46-13-29



Am27C010

1 Megabit (131,072 x 8-Bit) CMOS EPROM

Advanced Micro **Devices**

DISTINCTIVE CHARACTERISTICS

- Easy upgrade from 28-Pin JEDEC EPROMs
- Fast access time-100 ns
- Low power consumption:
 - 100 µA maximum standby current
- Programming voltage: 12.75 V
- Single +5 V power supply
- Compact 32-Pin DIP package requires no hardware change for upgrades to 8 megabits
- JEDEC-approved pinout
- ±10% power supply tolerance standard on most speeds
- Fast Flashrite[™] programming
- Latch-up protected to 100 mA from -1 V to

GENERAL DESCRIPTION

The Am27C010 is a 1 megabit, ultraviolet erasable programmable read-only memory. It is organized as 128K words by 8 bits per word, operates from a single +5 V supply, has a static standby mode, and features fast single address location programming. Products are available in windowed ceramic DIP and LCC packages, as well as plastic one-time programmable (OTP) packages.

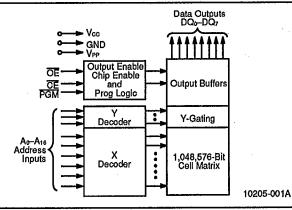
Typically, any byte can be accessed in less than 100 ns, allowing operation with high-performance microprocessors without any WAIT states. The Am27C010 offers

separate Output Enable (OE) and Chip Enable (CE) controls, thus eliminating bus contention in a multiple bus microprocessor system.

AMD's CMOS process technology provides high speed, low power, and high noise immunity. Typical power consumption is only 100 mW in active mode, and 250 μW in standby mode.

All signals are TTL levels, including programming signals. Bit locations may be programmed singly, in blocks, or at random.

BLOCK DIAGRAM



PRODUCT SELECTOR GUIDE

Family Part No.	Am27C010				
Ordering Part No:					
±5% Vcc Tolerance	-105	-125			-255
±10% Vcc Tolerance		-120	-150	-200	-250
Max. Access Time (ns)	100	120	150	200	250
CE (E) Access (ns)	100	120	150	200	250
OE (G) Access (ns)	50	50	65	. 75	100

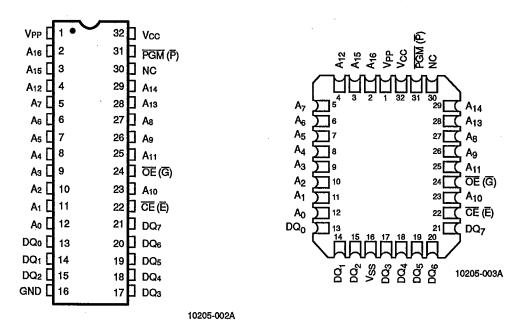
Amendment/0 Publication# 10205 Rev. C Issue Date: March 1991

CONNECTION DIAGRAMS Top View

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DIP

LCC*

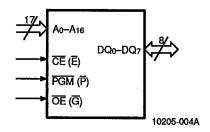


*Also available in a 32-pin rectangular Plastic Leaded Chip Carrier.

Notes

- 1. JEDEC nomenclature is in parenthesis.
- 2. The 32-pin DIP to 32-pin LCC configuration varies from the JEDEC 28-pin DIP to 32-pin LCC configuration.

LOGIC SYMBOL



PIN DESCRIPTION

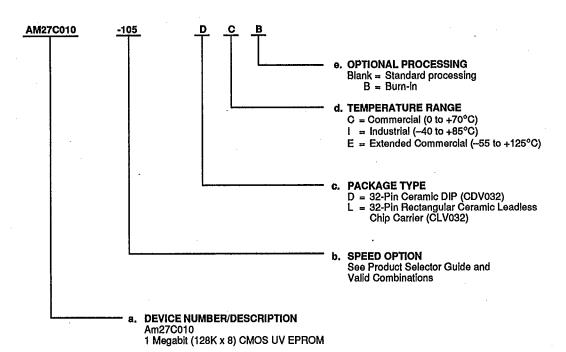
A0-A16	Address Inputs	PGM (P)	Program Enable Input
CE (E)	Chip Enable Input	Vcc	Vcc Supply Voltage
DQ ₀ -DQ ₇	Data Input/Outputs	Vpp	Program Supply Voltage
ŌĒ (Ġ)	Output Enable Input	GND	Ground
		NC	No Internal Connect

ORDERING INFORMATION Standard Products

T-46-13-29

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is a. Device Number b. Speed Option c. Package Type d. Temperature Range

Optional Processing



Valid Combinations						
AM27C010-105	DC, DCB					
AM27C010-120	DC, DCB, DI,					
AM27C010-125	DIB, LC, LI					
AM27C010-150	DC, DCB, DE,					
AM27C010-200	DEB, DI, DIB, LC, LCB, LI,					
AM27C010-255	LIB, LE, LEB					

Valid Combinations

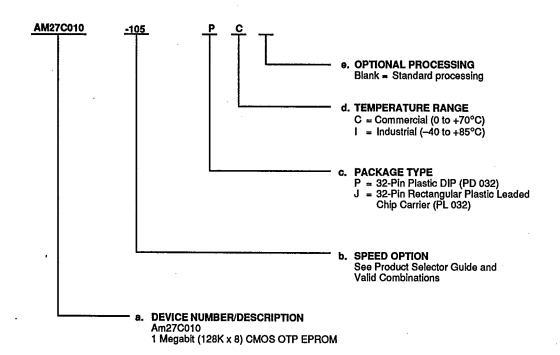
Valid Combinations list configurations planned to be supported in volume for this device. Consult the lo-cal AMD sales office to confirm availability of specific valid combinations or to check on newly released combinations.

ORDERING INFORMATION OTP Products

T-46-13-29

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

a. Device Number
b. Speed Option
c. Package Type
d. Temperature Range
e. Optional Processing



Valid Combinations			
AM27C010-105			
AM27C010-120]		
AM27C010-125			
AM27C010-150	PC, JC, PI, JI		
AM27C010-200			
AM27C010-255	1		

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check on newly released combinations.

MILITARY ORDERING INFORMATION **APL Products**

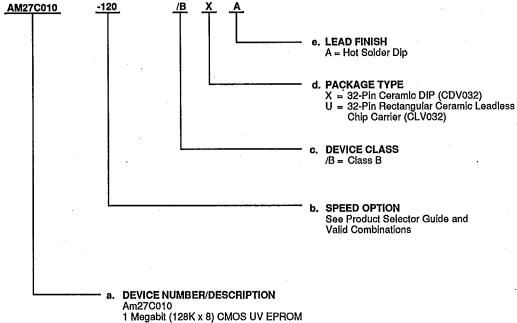
T-46-13-29

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. The order number (Valid Combination) is formed by a combination of:

a. Device Number

Speed Option **Device Class**





Valid Combinations					
AM27C010-120					
AM27C010-150	/BXA, /BUA				
AM27C010-200	/BAA, /BUA				
AM27C010-250					

For other Surface Mount Package options, contact NVD Military Marketing.

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Con-sult the local AMD sales office to confirm availability of specific valid combinations, or to check on newly released combinations.

Group A Tests

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

FUNCTIONAL DESCRIPTION

Erasing the Am27C010

In order to clear all locations of their programmed contents, it is necessary to expose the Am27C010 to an ultraviolet light source. A dosage of 15 W seconds/cm² is required to completely erase an Am27C010. This dosage can be obtained by exposure to an ultraviolet lamp -wavelength of 2537 Angstroms (A) -with intensity of 12,000 μW/cm² for 15 to 20 minutes. The Am27C010 should be directly under and about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the Am27C010, and similar devices, will erase with light sources having wavelengths shorter than 4000 Å. Although erasure times will be much longer than with UV sources at 2537Å, nevertheless the exposure to fluorescent light and sunlight will eventually erase the Am27C010 and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package window should be covered by an opaque label or substance.

Programming the Am27C010

Upon delivery, or after each erasure, the Am27C010 has all 1,048,576 bits in the "ONE", or HIGH state. "ZE-ROs" are loaded into the Am27C010 through the procedure of programming.

The programming mode is entered when $12.75 \pm 0.25 \text{ V}$ is applied to the VPP pin, CE and PGM are at VL and OE is at VIH.

For programming, the data to be programmed is applied 8 bits in parallel to the data output pins.

The Flashrite programming algorithm (shown in Figure 1) reduces programming time by using initial 100 µs pulses followed by a byte verification to determine whether the byte has been successfully programmed. If the data does not verify, an additional pulse is applied for a maximum of 25 pulses. This process is repeated while sequencing through each address of the EPROM.

The Flashrite programming algorithm programs and verifies at Vcc = 6.25 V and Vpp = 12.75 V. After the final address is completed, all bytes are compared to the original data with Vcc = Vpp = 5.25 V.

Program Inhibit

Programming of multiple Am27C010s in parallel with different data is also easily accomplished. Except for CE, all like inputs of the parallel Am27C010 may be common. A TTL low-level program pulse applied to an Am27C010 $\overline{\text{CE}}$ input with $V_{PP} = 12.75 \pm 0.25 \text{ V}$, $\overline{\text{PGM}}$ LOW, and OE HIGH will program that Am27C010. A high-level CE input inhibits the other Am27C010s from being programmed.

Program Verify

A verify should be performed on the programmed bits to determine that they were correctly programmed. The T-46-13-29

verify should be performed with OE and CE at VIL, PGM at VIH, and VPP between 12.5 V and 13.0 V.

Auto Select Mode

The auto select mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmed with its corresponding programming algorithm. This mode is functional in the 25° C $\pm 5^{\circ}$ C ambient temperature range that is required when programming the Am27C010.

To activate this mode, the programming equipment must force 12.0 ± 0.5 V on address line A9 of the Am27C010. Two identifier bytes may then be sequenced from the device outputs by toggling address line Ao from VIL to VIH. All other address lines must be held at VIL during auto select mode.

Byte 0 (Ao = VIL) represents the manufacturer code, and Byte 1 (Ao = VIH), the device identifier code. For the Am27C010, these two identifier bytes are given in the Mode Select table. All identifiers for manufacturer and device codes will possess odd parity, with the MSB (DQ7) defined as the parity bit.

Read Mode

The Am27C010 has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable (CE) is the power control and should be used for device selection. Output Enable (\overline{OE}) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (tacc) is equal to the delay from CE to output (tce). Data is available at the outputs to after the falling edge of OE, assuming that CE has been LOW and addresses have been stable for at least tACC - tOE.

Standby Mode

The Am27C010 has a CMOS standby mode which reduces the maximum Vcc current to 100 µA. It is placed in CMOS-standby when \overline{CE} is at $V_{CC} \pm 0.3$ V. The Am27C010 also has a TTL-standby mode which reduces the maximum Vcc current to 1.0 mA. It is placed in TTL-standby when CE is at VIH. When in standby mode. the outputs are in a high-impedance state, independent of the OE input.

Output OR-Tieing

To accommodate multiple memory connections, a twoline control function is provided to allow for:

- 1. Low memory power dissipation, and
- 2. Assurance that output bus contention will not occur.

It is recommended that CE be decoded and used as the primary device-selecting function, while OE be made a common connection to all devices in the array and connected to the READ line from the system control bus.

This assures that all deselected memory devices are in their low-power standby mode and that the outut pins are only active when data is desired from a particular memory device.

System Applications

During the switch between active and standby conditions, transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a 0.1 µF ceramic capacitor (high frequency, low inherent inductance) should be used on each device between Vcc and GND to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a 4.7 μF bulk electrolytic capacitor should be used between Vcc and GND for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

Mode Select Table

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Mode	Pins	CE	ŌĒ	PGM	Ao	A 9	Vpp	Outputs
Read		VIL	VIL	Х	Х	X	X	Dout
Output Disable		VIL	ViH	X	X	Х	Х	High Z
Standby (TTL)		ViH	X	Х	Х	Х	X	High Z
Standby (CMOS)		Vcc ± 0.3 V	Х	Х	X	. X	Х	High Z
Program			ViH	VIL	Х	Х	Vpp	Din
Program Veri	fy	VIL	ViL	ViH	Х	X	Vpp	Dout
Program Inhibit		ViH	X	X	X.	Х	Vpp	High Z
Auto Select Manufacturer Code		VIL	VIL	X	VII.	. VH	Х	01H
(Note 3)	Device Code	V _{IL}	VIL	Х	ViH	VH	Х	OEH

Notes:

- 1. X can be either VIL or VIH
- 2. $V_H = 12.0 V \pm 0.5 V$
- 3. $A_1 A_8 = A_{10} A_{16} = ViL$
- 4. See DC Programming Characteristics for VPP voltage during programming.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature: **OTP Products** -65 to +125°C All Other Products -65 to +150°C **Ambient Temperature** with Power Applied -55 to +125°C Voltage with Respect to Ground:

All pins except A9, VPP, and Vcc (Note 1) -0.6 to Vcc +0.6 V

As and VPP (Note 2) -0.6 to 13.5 V Vcc -0.6 to 7.0 V

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. This is a stress rating only; functional operation of the devices at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

Notes:

- 1. During transitions, the input may overshoot GND to -2.0 V for periods of up to 20 ns. Maximum DC voltage on input and I/O may overshoot to Vcc + 2.0 V for periods up to 20 ns.
- 2. During transitions, As and VPP may overshoot GND to -2.0 V for periods of up to 20 ns. As and VPP must not exceed 13.5 V for any period of time.

T-46-13-29 **OPERATING RANGES** Commercial (C) Devices Case Temperature (Tc) 0 to +70°C Industrial (I) Devices Case Temperature (Tc) -40 to +85°C

Extended Commercial (E) Devices Case Temperature (Tc) -55 to +125°C

Military (M) Devices Case Temperature (Tc) -55 to +125°C

Supply Read Voltages: Vcc for Am27C010-XX5 +4.75 to +5.25 V Vcc for Am27C010-XX0 +4.50 to +5.50 V

Operating ranges define those limits between which the functionality of the device is guaranteed,

DC CHARACTERISTICS over operating ranges unless otherwise specified T-46-13-29 (Notes 1, 4, 5 & 8) (for APL products, Group A, Subgroups 1, 2, 3, 7 and 8 are tested unless otherwise noted)

Parameter Symbol	Parameter Description	Test Conditions		Min.	Max.	Unit
	MOS Inputs					<u> </u>
Vон	Output HIGH Voltage	Іон =400 μΑ		2.4		V
Vol	Output LOW Voltage	loL = 2.1 mA			0.45	٧
ViH	Input HIGH Voltage	· · · · · · · · · · · · · · · · · ·		2.0	Vcc + 0.5	٧
V _{IL}	Input LOW Voltage			-0.5	+0.8	V
lu	Input Load Current	Vin = 0 V to Vcc	C/I Devices		1.0	μΑ
			E/M Devices		1.0	μΛ
lLO	Output Leakage Current	Vout = 0 V to Vcc	C/I Devices		10	μА
			E/M Devices		10	μ,
lcc1	Vcc Active Current (Note 5)	CE = V _{IL} , f = 5 MHz	C/I Devices	ì	30	mA
		lout = 0 mA (Open Outputs)	E/M Devices		60	
lcc2	Vcc Standby Current	CE = VIH	C/I Devices		1.0	mA
			E/M Devices		1.0	
ÎPP1	V _{PP} Current During Read (Note 6)	CE = OE = VIL, VPP =	Vcc		100	μА
CMOS Inpu	its					
Vон	Output HIGH Voltage	Іон = −400 μА		2.4		>
Vol	Output LOW Voltage	loL = 2.1 mA			0.45	٧
VIH	Input HIGH Voltage			Vcc - 0.3	Vcc + 0.3	٧
VIL	Input LOW Voltage			-0.5	. +0.8	٧
lu	Input Load Current	Vin = 0 V to +Vcc	C/I Devices		1.0	μА
			E/M Devices		1.0	μл
lLO	Output Leakage Current	Vout = 0 V to +Vcc	C/I Devices		10	μΑ
			E/M Devices		10	μΛ
lcc ₁	Vcc Active Current (Note 5)	CE = V _{IL} , f = 5 MHz,	C/I Devices		30,	mA
	,	lour = 0 mA (Open Outputs)	E/M Devices		60	
lcc2	Vcc Standby Current	CE = Vcc ± 0.3 V	C/I Devices		100	
			E/M Devices		100	μΑ
IPP1	VPP Current During Read (Note 6)	CE = OE = VIL, VPP =	Vcc		100	μΑ

CAPACITANCE (Notes 2, 3, & 7)

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Parameter			CD	V032	CLV	032	
Symbol	Parameter Description	Test Conditions	Тур.	Max.	Тур.	Max.	Unit
Cin	Input Capacitance	V _{IN} = 0 V	10	12	8	10	рF
Соит	Output Capacitance	Vout = 0 V	12	15	9	12	рF

Notes:

- 1. Vcc must be applied simultaneously or before VPP, and removed simultaneously or after VPP.
- 2. Typical values are for nominal supply voltages.
- 3. This parameter is only sampled and not 100% tested.
- 4. Caution: The Am27C010 must not be removed from, or inserted into, a socket or board when Vcc or VPP is applied.
- 5. Icc1 is tested with $\overline{OE} = V_{IH}$ to simulate open outputs.
- 6. Maximum active power usage is the sum of Icc and IPP.
- 7. $T_A = +25$ °C, f = 1 MHz.
- During transitions, the inputs may overshoot to -2.0 V for periods less than 20 ns.
 Maximum DC voltage on output pins may overshoot to Vcc + 2.0 V for periods less than 20 ns.

SWITCHING CHARACTERISTICS over operating ranges unless otherwise specified (Notes 1, 3, & 4) (for APL products, Group A, Subgroups 9, 10, and 11 are tested unless otherwise noted)

				Am27C010						
JEDEC	Standard	Parameter Description	Test Conditions		-105	-120, -125	-150	-200	-250, -255	Unit
tavav	tACC	Address to	7F 0F V	Min,						
		Output Delay	CE = OE = VIL	Max.	100	120	150	200	250	ns
telav	tce	Chip Enable	OF 1/2	Min.						
		to Output Delay	OE = VIL	Max.	100	120	150	200	250	ns
tglav	toe	Output Enable to	CE = VIL	Min.	-	-	_	-	-	
		Output Delay	GE = VIL	Max.	50	50	65	75	100	ns
tehoz, tghoz	tor	Chip Enable HIGH or Output Enable HIGH, whichever		Min.	0	o	0	0	0	
		comes first, to Output Float (Note 2)		Max,	35	35	35	40	40	ns
taxqx			Mín.	0	0	0	0	0		
		Addresses, CE, or OE, whichever occurred first		Max.	-	-	-	-		ns

Notes:

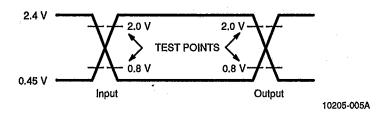
- 1. Vcc must be applied simultaneously or before VPP, and removed simultaneously or after VPP.
- 2. This parameter is only sampled, not 100% tested.
- 3. Caution: The Am27C010 must not be removed from, or inserted into, a socket when VPP or Vcc is applied.
- Output Load: 1 TTL gate and C_L = 100 pF Input Rise and Fall Times: 20 n

Input Pulse Levels: 0.45 to 2.4 V

Timing Measurement Reference Level—Inputs: 0.8 V and 2 V

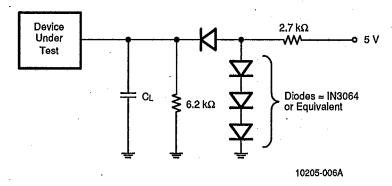
SWITCHING TEST WAVEFORM

T-46-13-29



AC Testing: Inputs are driven at 2.4 V for a Logic "1" and 0.45 V for a Logic "0". Input pulse rise and fall times are ≤ 20 ns.

SWITCHING TEST CIRCUIT



CL = 100 pF including jig capacitance

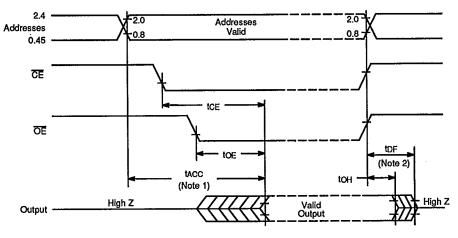
KEY TO SWITCHING WAVEFORMS

T-46-13-29

WAVEFORM	INPUTS	OUTPUTS
	Must Be Steady	Will Be Steady
	May Change from H to L	Will Be Changing from H to L
_////	May Change from L to H	Will Be Changing from L to H
	Don't Care, Any Change Permitted	Changing, State Unknown
\longrightarrow	Does Not Apply	Center Line is High Impedance "Off" State

KS000010

SWITCHING WAVEFORM



Notes:

10205-007B

- 1. $\overline{\text{OE}}$ may be delayed up to tACC-tOE after the falling edge of $\overline{\text{CE}}$ without impact on tACC.
- 2. tDF is specified from \overline{OE} or \overline{CE} , whichever occurs first.

PROGRAMMING FLOW CHART

T-46-13-29

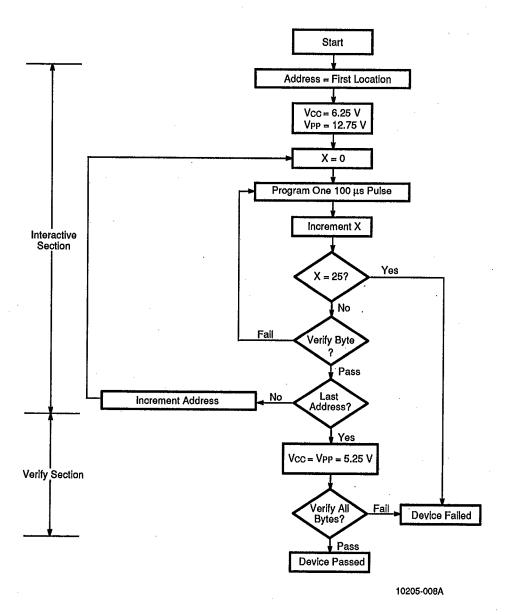


Figure 1. Flashrite Programming Flow Chart

T-46-13-29

DC PROGRAMMING CHARACTERISTICS (T_A = +25°C ±5°C) (Notes 1, 2, & 3)

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
lu	Input Current (All Inputs)	VIN = VIL OF VIH		10.0	μΑ
VIL	Input LOW Level (All Inputs)		-0.3	0.8	٧
VIH	Input HIGH Level		2.0	Vcc + 0.5	٧
Vol	Output LOW Voltage During Verify	lo _L = 2.1 mA		0.45	٧
Voн	Output HIGH Voltage During Verify	loн = -400 μA	2.4		٧_
VH	As Auto Select Voltage		11.5	12.5	٧
lcc	Vcc Supply Current (Program & Verify)			50	mA
Ірр	V _{PP} Supply Current (Program)	CE = V _I L, OE = V _I H		30	mA
Vcc	Flashrite Supply Voltage		6.00	6.50	V
Vpp	Flashrite Programming Voltage		12.5	13.0	٧

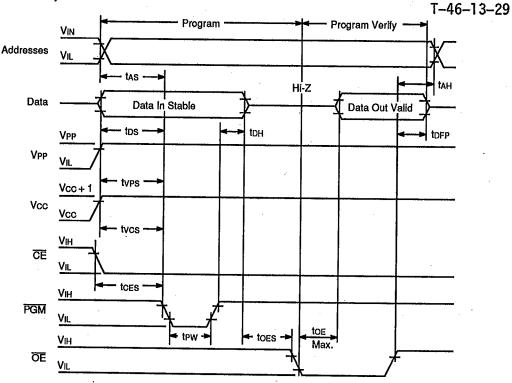
SWITCHING PROGRAMMING CHARACTERISTICS ($T_A = +25$ °C ± 5 °C) (Notes 1, 2, & 3)

Parameter Symbols					
JEDEC	Standard	Parameter Description	Min.	Max.	Unit
tavel	tas	Address Setup Time	2		μs
tozgl	toes	OE Setup Time	2		μs
tovel	tos	Data Setup Time	2		μs
tghax	tah	Address Hold Time	0		μs
t EHDX	tрн	Data Hold Time	2	<u> </u>	μs
tgнаz	t _{DFP}	Output Enable to Output Float Delay	0	130	ns
tvps	tvps	V _{PP} Setup Time	2		μs
teleh1	tew	PGM Initial Program Pulse Width	95	105	μs
tvcs	tvcs	Vcc Setup Time	2		μs
t ELPL	tces	CE Setup Time	2		μs
tglav	toe	Data Valid from OE		150	ns

Notes:

- 1. Vcc must be applied simultaneously or before Vpp, and removed simultaneously or after Vpp.
- When programming the Am27C010, a 0.1 μF capacitor is required across Vpp and ground to suppress spurious voltage transients which may damage the device.
- 3. Programming characteristics are sampled but not 100% tested at worst-case conditions.

INTERACTIVE AND FLASHRITE PROGRAMMING ALGORITHM WAVEFORM (Notes 1 & 2)



Notes:

10205-009A

- 1. The input timing reference level is 0.8 V for V_{IL} and 2 V for V_{IH} .
- 2. top and topp are characteristics of the device, but must be accommodated by the programmer.